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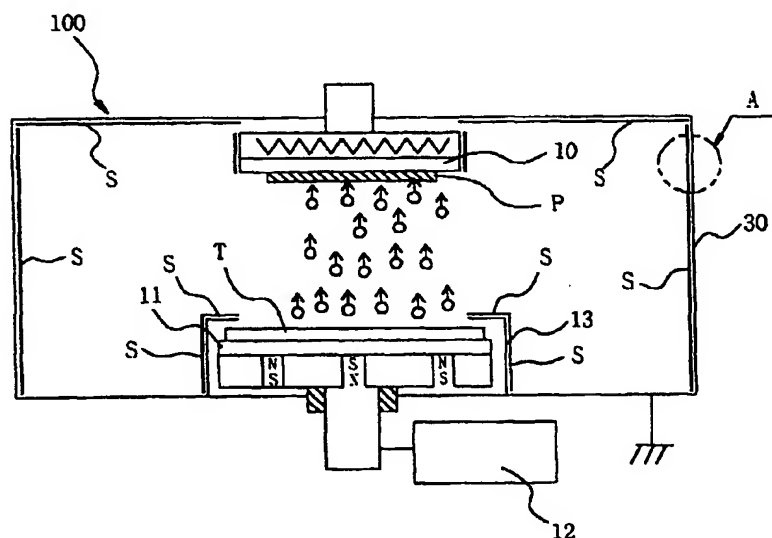
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(54) Title: THIN FILM FORMING APPARATUS



(57) Abstract: The present invention relates to a thin forming apparatus, i.e. an apparatus for forming thin films of various materials on substrates, for example, in processes of fabricating semiconductor wafers or liquid crystal displays (LCDs). The thin film forming apparatus comprises a substrate support for mounting a substrate on which a thin film is to be formed, and a chamber that encloses the substrate support and has proper operation conditions. Then, adsorption means constructed by applying a ductile metal material such as indium, tin, lead or antimony on a metal or synthetic resin base material are attached to surfaces of components within the thin film forming apparatus except the substrate. Accordingly, it is possible to fundamentally prevent failure of formation of a thin film due to adhesion of a portion of an unnecessary thin film, which has been formed on and then peeled off from the surfaces of the components, to the substrate.